



DM(R) -V	SPECIFICATION	FILE No. REV. Page	:	E-\ 1	V-AC B /	005 5
1. Style: This specification (describes "DUAL IN-LINE PA(CKAGE SWITCHE	S"	mai	nlv u	ised

as signal switch of electric devices with the general requirements of mechanical and electrical characteristics.

1.1 Operating Temperature Range : -40° C ~ $+85^{\circ}$ C

1.2 Storage Temperature Range $: -40^{\circ}C \sim +85^{\circ}C$

1.3 The shelf life of product is within 6 months.

2. Current Range :

- 2.1 Non-Switching : 100mA, 50V DC
- 2.2 Switching : 25mA , 24V DC
- 3. Type of Actuation: Actuated by sliding

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4. Test Sequence

	ITEM	DESCRIPTION	TEST CONDITIONS	REQUIREMENTS
PERFORMANCE	1	Visual Examination	By visual examination check without any out pressure & testing.	There shall be no defects that affect the serviceability of the product.
	2	Contact Resistance	 To be measured between the two terminals associated with each switch pole. Measurements shall be made with a 1kHz shall current contact resistance meter. 	50mΩ max. (initial)
FRIC	3	Insulation Resistance	500V DC, 1 minute ± 5 sec.	100MΩ min.
ELECT	4	Dielectric withstand- ing Voltage	 ①500V AC (50Hz or 60 Hz) shall be applied between all the adjacent terminals and between the terminal and the frame for 1 minute. ②Cut off current : 0.5mA max. 	There shall be no breakdown or flashover.
	5	Capacitance	1 MHz ± 10 kHz	5 pF max.
MECHANICAL PERFORMANCE	6	Operation Force	Applied in the direction of operation. ON→OFF OFF→ON	1000gf max (9.8N max)



	7	Stop Strength	A static load of 1 operating directio operated for a pe	kgf is applied n and pulling riod of 15 sed	l in the direction conds.	There shall be no sign of damage mechanically.
		Soldering	1.Soldering Temp	erature :		
			PROD SERIES	TEMP	TIME	
			THROUGH HOLE TYPE NDI(R)-V	260°∁±5°∁	5±1 sec.	
	8	Heat	DM(R) \ DL(R)-V	SEE P/	AGE 4/4	As shown in item 2~6
MECHANICAL PERFORMANCE		Resistance	 2.Duration of Solder Immersion: 5±1 sec. 3.Frequency of Soldering Process: 2 times max. 			
	9	Vibration	Shall be vibrated in accordance with Method 201A of MIL-STD-202F ①Frequency: 10-55-10 Hz 1 min/cycle. ②Direction: 3 vertical directions including the direction of operation. ③Test Time: 2 hours each direction			As shown in item 2~6
	10	Shock	Shall be shocked in accordance with Method 213B condition A of MIL-STD-202F ①Acceleration: 50G. ②Action Time : 11 ± 1 m sec. ③Testing Direction: 6 sides. ④Test cycle : 3 times in each direction			As shown in item 2~6
	11	Solderability	 ①THROUGH HOLE TYPE Soldering Temperature:245±3°C Lead-Free solder : M705E JIS Z 3282 Class A (Tin 96.5%, Silver 3%, Copper 0.5%) ②Flux: 5-10 seconds. ③Duration of solder Immersion: 3±0.5 sec. ④ SMT TYPE SEE PAGE 4/4 			No anti-soldering and the coverage of dipping into solder must more than 75% was requested.



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DURABILITY	12	Operation Life	Measurements shall be made following the test set forth below: ①25 mA, 24V DC resistive load ②Rate of Operation: 15~20 cycles/ minute ③Cycle of Operation: 2000 cycles.	 As show in item 3,4 Contact Resistance: 100mΩ max. (final-after test)
WEATHER-PROOF	13	Resistance Low Temperature	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before measurements are made : 1.Temperature : -40°C ±3°C 2.Time: 96 hours	As shown in item 2~6
	14	Resistance High Temperature	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before measurements are made : 1.Temperature : 85°C ±2°C 2.Time: 96 hours	1.As shown in item 3~6 2.Contact Resistance: 100mΩ max.
	15	Resistance Humidity	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before measurements are made : ①Temperature : 40°C ±2°C ②Relative Humidity :90~95% ③Time: 96 hours	 1.As shown in item 4,6 2.Contact Resistance: 100mΩ max. 3.Insulation Resistance: 10MΩ min.



There are cases where board's temperature greatly differs from switch's surface temperature depending on board's material, size, thickness, etc. Care, therefore, should be used not to allow switch's surface temperature to exceed 260° C.

Manual Soldering

Soldering Temperature	Max.350 ℃	
Continuous Soldering Time	Max. 5 seconds	

- Precautions in Handling
 - 1. Care should be exercised so that flux from the upper part of the printed circuit board does not adhere to the switch.
 - 2. Don't clean the switch body except with top tape sealed type, which can only spray of cleaning method from top of s/w.
 - 3. Please make sure that there is no flux rose over the surface of the PCB



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■ Notes on storage conditions:

Do not store in the following environment or it may affect product's function and solderbility:

- 1. temperature of -10 (max) ~ +40 (min) $^{\circ}$ C & humidity at 85% (min)
- 2. environment with corrosive gas
- 3. storage over 6 months
- 4. place of direct sunlight

Store with proper packaging conditions and to avoid loading heavy force

We suggest to use the products within 3 months or at least 6 months.

After opening the package, the rest products must be stored in the appropriate moisture-proof & airtight environment